

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chun-Chieh Wu	07/31/2007
Hung-Chun Chu	07/31/2007
RECEIVING PARTY DATA	
Name:	ASUSTeK COMPUTER INC.
Street Address:	4Fl., No. 150, Li-Te Rd., Peitou,
City:	Taipei
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11836787
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	22179-US-PA
NAME OF SUBMITTER:	Belinda Lee
Total Attachments: 2	
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CH \$40.00 11836787

ASSIGNMENT

WHEREAS,

1. Chun-Chieh Wu

2. Hung-Chun Chu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **HEAT SINK BACKPLATE MODULE, CIRCUIT BOARD, AND ELECTRONIC APPARATUS HAVING THE SAME**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, ASUSTeK COMPUTER INC.

of 4Fl., No. 150, Li-Te Rd., Peitou, Taipei, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chun-Chieh Wu Date: 2007. 7. 31
Sole or First Joint Inventor: Chun-Chieh Wu

Signature: Hung-Chun Chu Date: 2007 / 7 / 31
Second Joint Inventor (if any): Hung-Chun Chu